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United States Patent [19]

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Smithers

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[54] **SPRING CLIP FOR RETAINING THERMAL CONTACT BETWEEN AN ELECTRONIC DEVICE PACKAGE AND A HEAT SINK**

4,964,198 10/1990 McCarthy 165/185 X
5,068,764 11/1991 Bland et al. 361/704
5,138,524 8/1992 Smithers 174/16.3 X

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Primary Examiner—Joel Sincavage
Attorney, Agent, or Firm—Jack A. Kanz

[73] Assignee: **Thermalloy, Inc.**, Dallas, Tex.

[57] **CLAIM**

[**] Term: **14 Years**

The ornamental design disclosed for a spring clip for retaining thermal contact between an electronic device package and a heat sink, as shown and described.

[21] Appl. No.: **13,459**

DESCRIPTION

[22] Filed: **Sep. 24, 1993**

[52] U.S. Cl. **D13/179; D8/395**

[58] Field of Search **D13/173, 179; D8/349, D8/354, 395; 361/704, 707, 717; 165/80.3, 185; 174/16.3; 24/458**

FIG. 1 is a front perspective view of a spring clip for retaining thermal contact between an electronic device package and a heat sink showing my new design;

FIG. 2 is a top plan view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

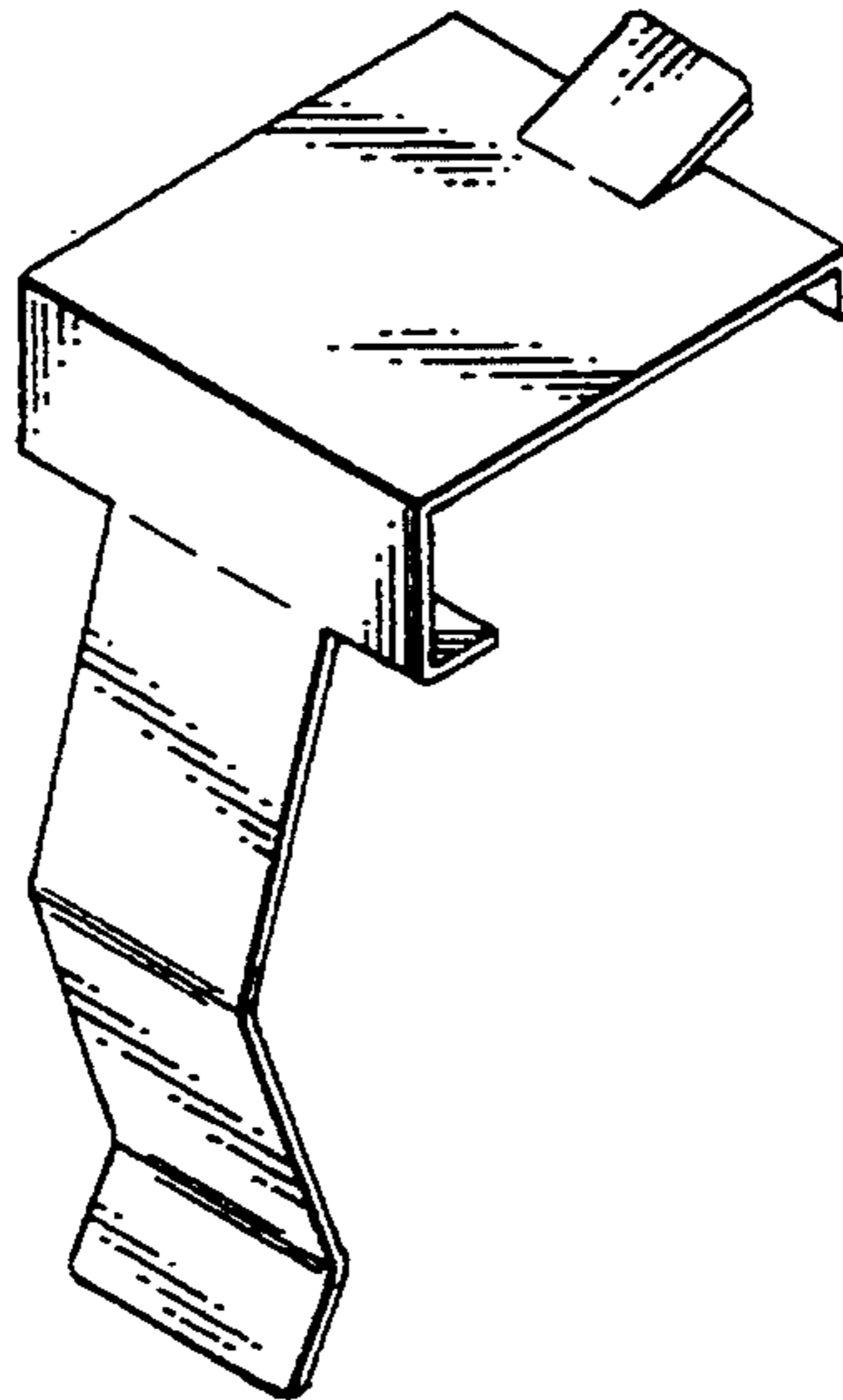
FIG. 5 is a side elevational view thereof, the opposite side view being a mirror image of the view of FIG. 5; and,

FIG. 6 is a bottom plan view of my spring clip for retaining thermal contact between an electronic device package and a heat sink.

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 275,178 8/1984 Yeater D8/349 X
D. 301,334 5/1989 Dupasquier et al. D13/179
D. 307,540 5/1990 McCarthy D13/179 X
2,724,882 11/1955 Poupitch 24/458 X



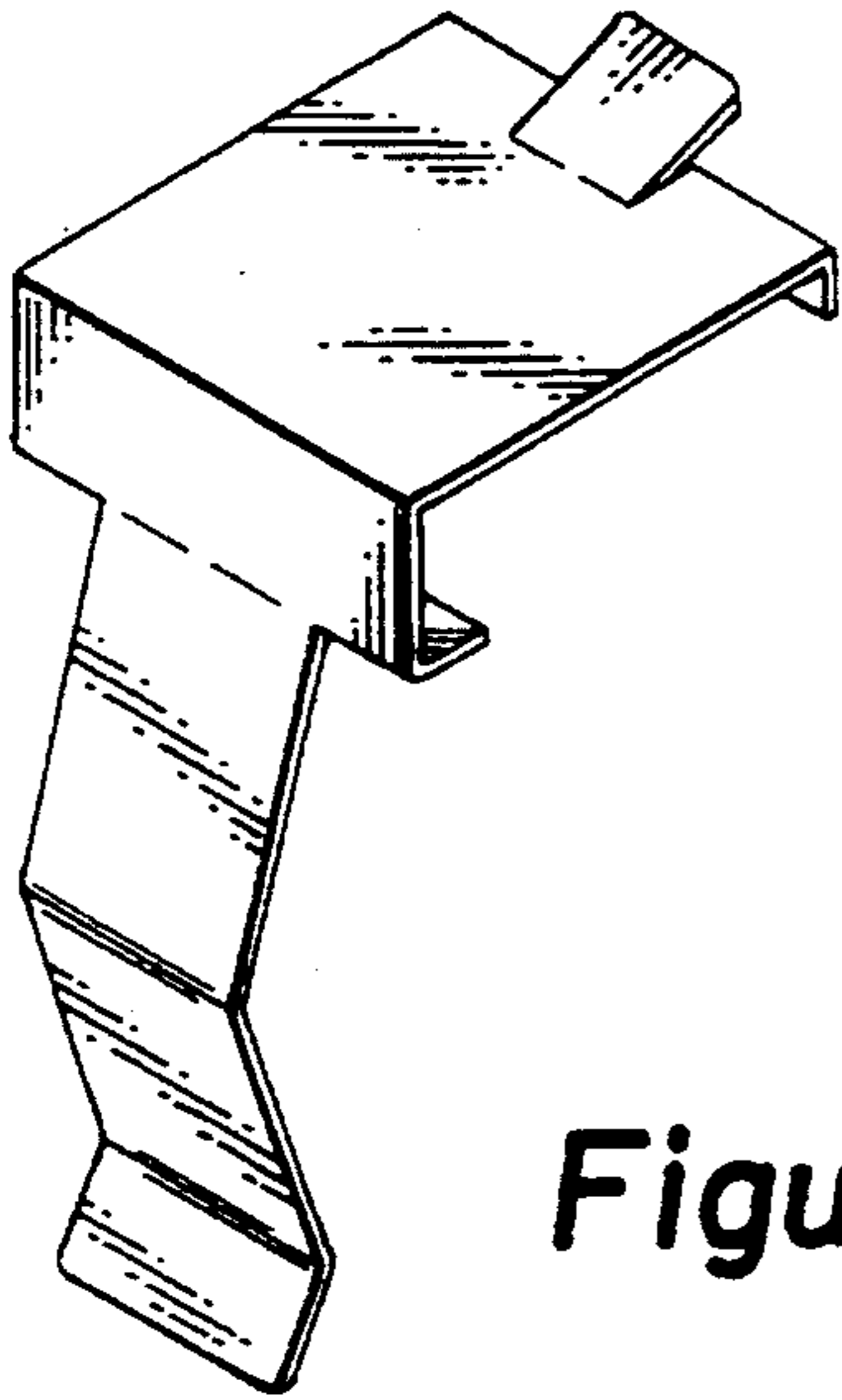


Figure 1

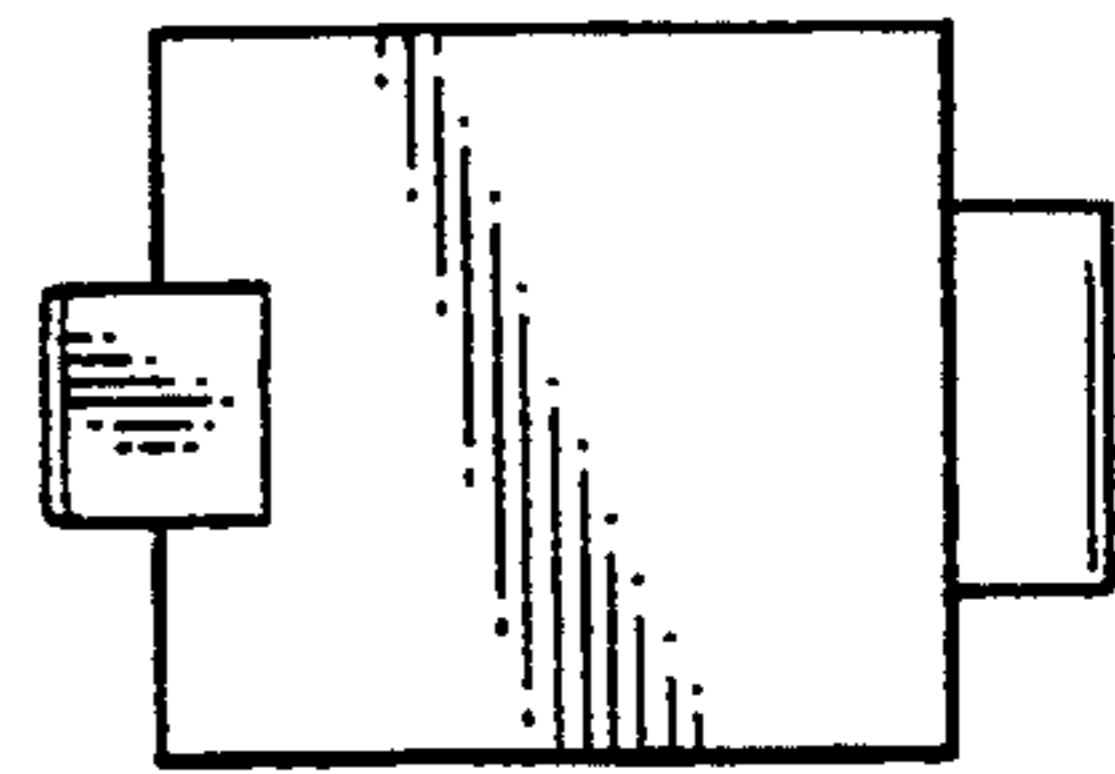


Figure 2

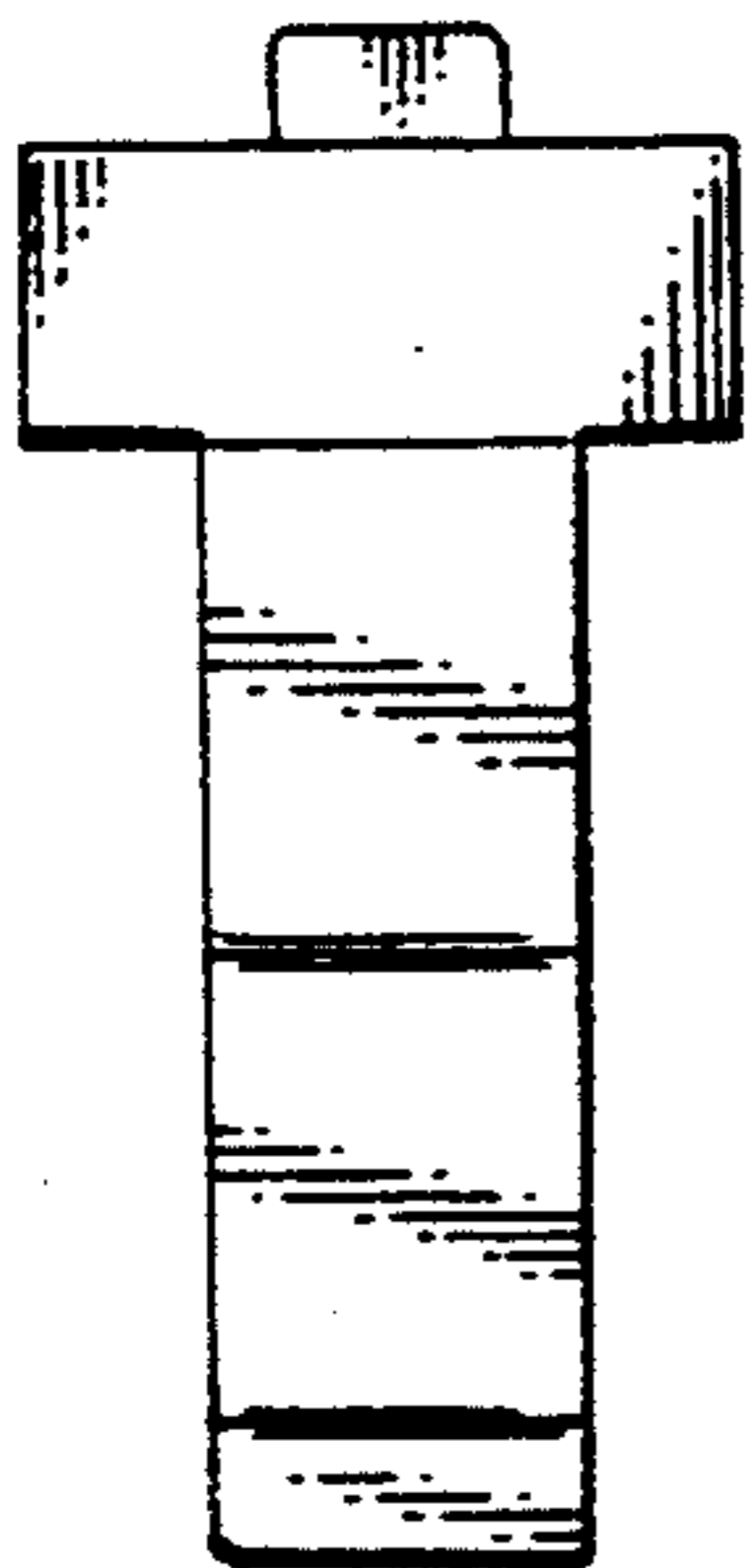


Figure 3

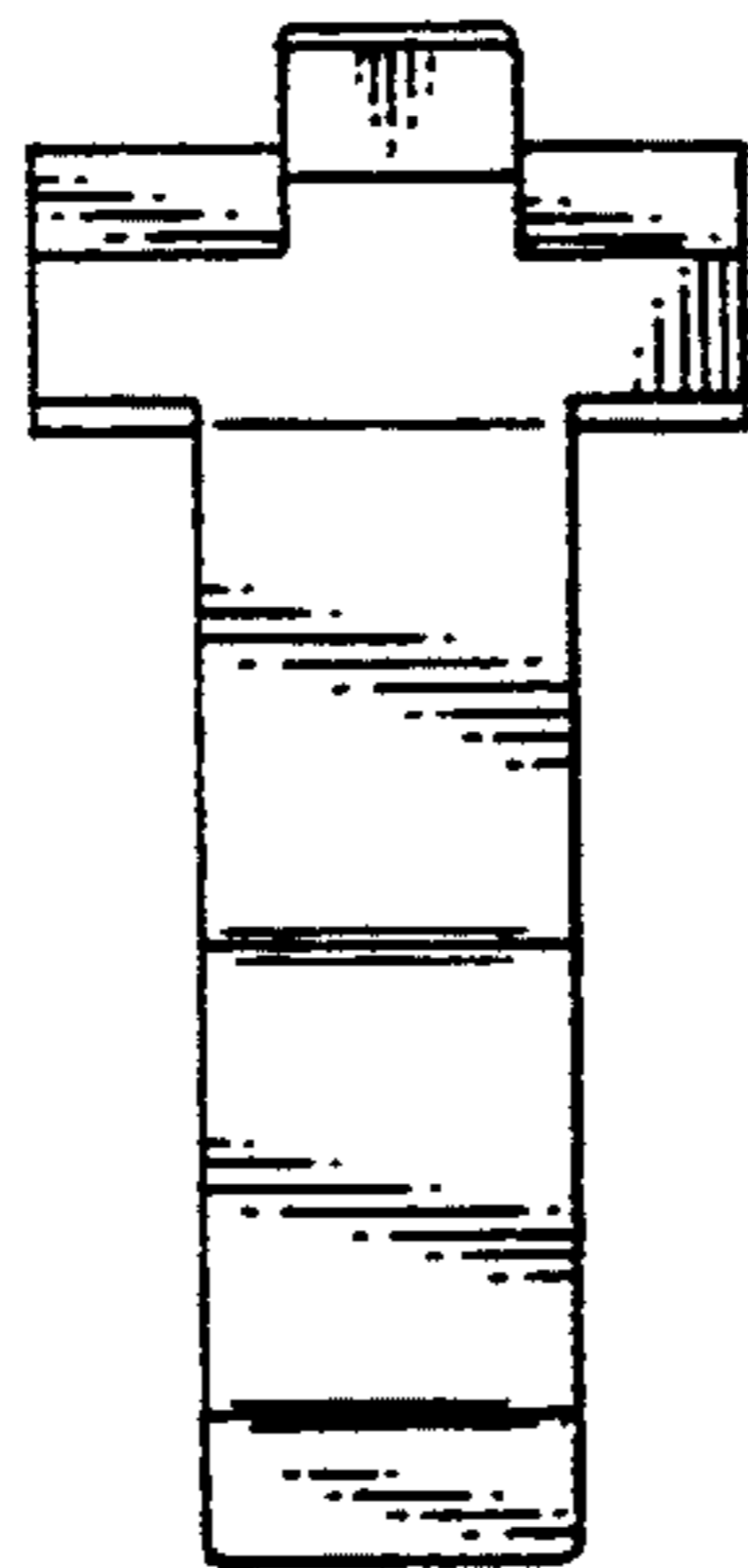


Figure 4

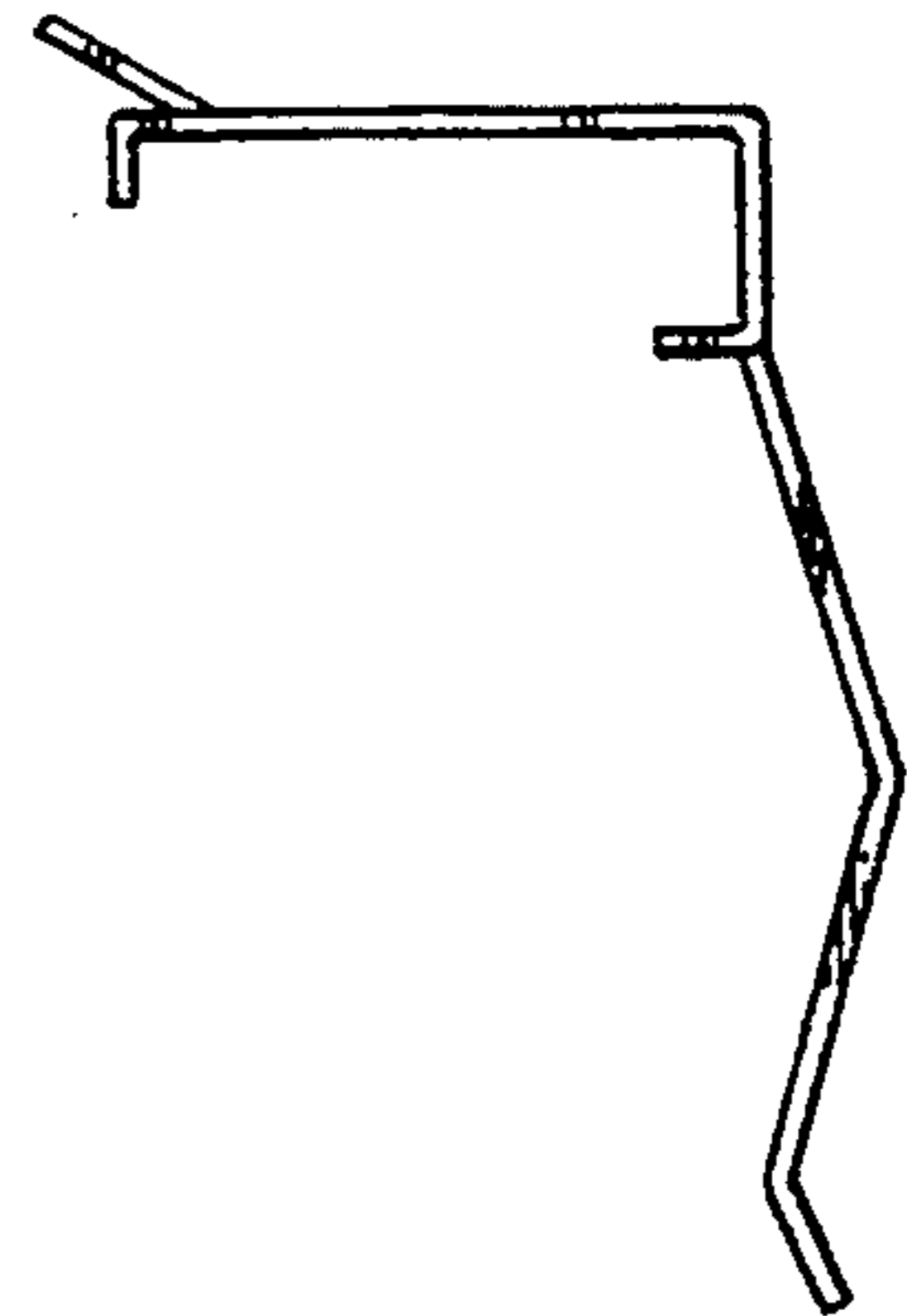


Figure 5

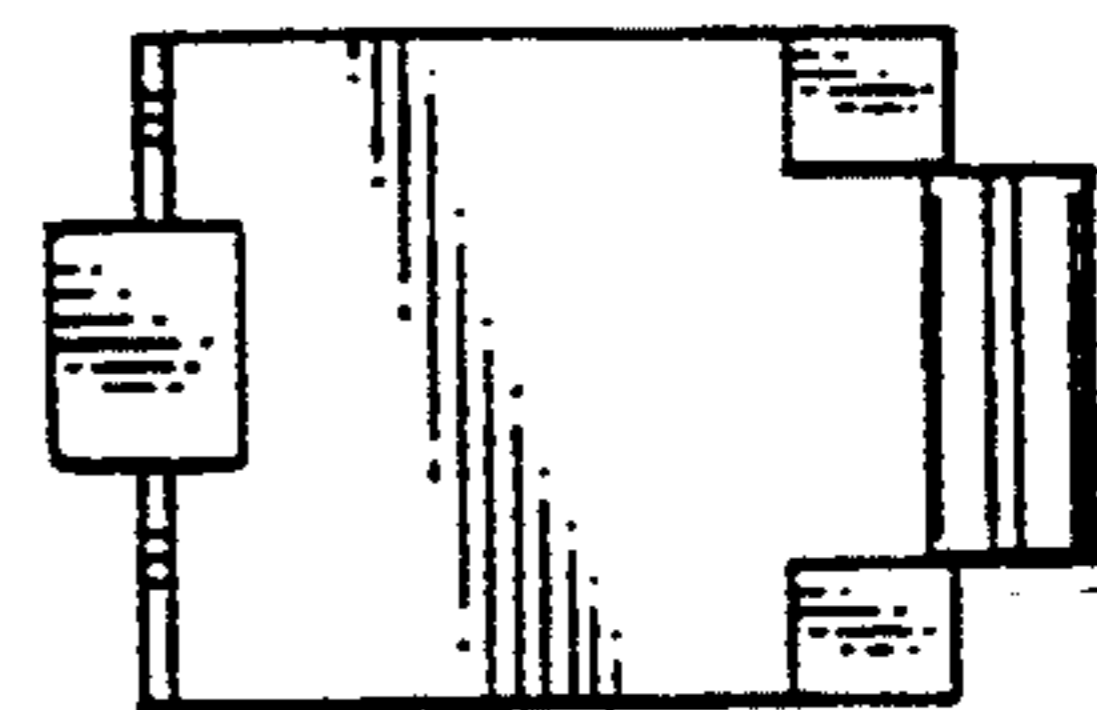


Figure 6